



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISK024NE2LM5	Issued	05. February 2022
MA#	MA004987036		
Package	PG-VSON-6-1	Weight*	13.02 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.234	1.80	1.80	17960	17960
leadframe	inorganic material	phosphorus	7723-14-0	0.001	0.01		101	
	non noble metal	zinc	7440-66-6	0.005	0.04		402	
	non noble metal	iron	7439-89-6	0.105	0.80		8046	
	non noble metal	copper	7440-50-8	4.254	32.67	33.52	326720	335269
wire	non noble metal	copper	7440-50-8	0.005	0.04	0.04	396	396
encapsulation	organic material	carbon black	1333-86-4	0.015	0.12		1189	
	plastics	epoxy resin	-	0.470	3.61		36080	
	inorganic material	silicondioxide	60676-86-0	4.677	35.93	39.66	359216	396485
leadfinish	non noble metal	tin	7440-31-5	0.169	1.30	1.30	12982	12982
plating	noble metal	silver	7440-22-4	0.197	1.51	1.51	15113	15113
solder	noble metal	silver	7440-22-4	0.010	0.07		739	
	non noble metal	tin	7440-31-5	0.019	0.15		1478	
	non noble metal	lead	7439-92-1	0.356	2.73	2.95	27344	29561
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.01		58	
	non noble metal	zinc	7440-66-6	0.003	0.02		231	
	non noble metal	iron	7439-89-6	0.060	0.46		4614	
	non noble metal	copper	7440-50-8	2.439	18.73	19.22	187331	192234
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com